

To: Commissioner of Patents and Trademarks  
Washington, D.C. 20231

Fr: George O. Saile, Reg. No. 19,572  
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6A1 2812  
# 2/205  
P. 30-01  
RECEIVED  
AUG 21 2001  
August 14 2001  
TECHNOLOGY CENTER 2800

Subject:.

Serial No. 09/863,224 05/24/01

Ming-Hsing Tsai, Jing-Cheng Lin,  
Shau-Lin Shue, Chen-Hua Yu

METHOD TO SOLVE VIA POISONING FOR  
POROUS LOW-K DIELECTRIC

Grp. Art Unit: 2812

#### INFORMATION DISCLOSURE STATEMENT

Enclosed is Form PTO-1449, Information Disclosure Citation  
In An Application.

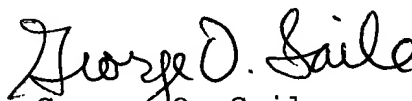
The following Patents and/or Publications are submitted to  
comply with the duty of disclosure under CFR 1.97-1.99 and  
37 CFR 1.56. Copies of each document is included herewith.

U.S. Patent 5,916,823 to Lou et al., "Method for Making  
Dual Damascene Contact," describes a method for forming a dual  
damascene structure with a low-k dielectric material.

U.S. Patent 6,074,942 to Lou, "Method for Forming a Dual  
Damascene Contact and Interconnect," describes a method of  
forming a dual damascene structure.

U.S. Patent 6,140,220 to Lin, "Dual Damascene Process and Structure with Dielectric Barrier Layer," describes a dual damascene structure with a dielectric layer, and process for manufacturing it.

Sincerely,

A handwritten signature in cursive script that reads "George O. Saile". The signature is written in dark ink and is positioned above the printed name and registration number.

George O. Saile,  
Reg. No. 19572